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AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A method for forming a package for an electrical device, said method comprising the steps of:

attaching a removable material to a surface of a conductive material;
forming isolated conductive features within said a conductive material;
attaching a removable material to said surface of said conductive material after said

isolated conductive features have been formed;
attaching encapsulant to said isolated conductive features and said removable

material; and

removing said removable material from said conductive features and said encapsulant.

- 2. (Original) The method for forming a package for the electronic device of claim 1, wherein said forming step includes patterning a surface of said conductive material with a material resistant to an etchant and etching said conductive material with said etchant.
- 3. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of forming a die attach pad within said conductive material.
- 4. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of coupling the device to said die attach pad.
- 5. (Original) The method for forming a package for an electronic device of claim 1, further comprising the step of electrically coupling an input/output portion of the device to said isolated conductive feature.
- 6. (Original) The method for forming a package for the electronic device of claim 1, further comprising the step of singulating individual packaged devices.

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- 7. (Original) The method of claim 1, wherein the removable material is water soluble adhesive.
- 8. (Original) The method of claim 7, wherein the removable material is removed with deionized water.
 - 9-15. (Canceled)
- 16. (New) The method of claim 1, wherein the removable material is a mold stencil that is used in said attaching encapsulant step.